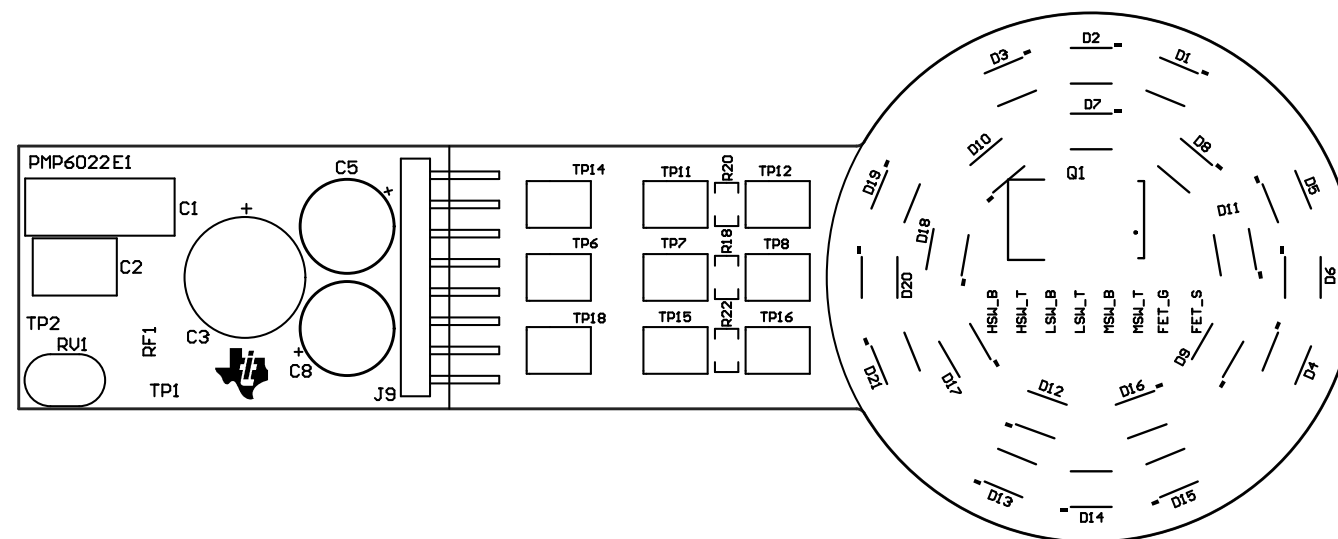
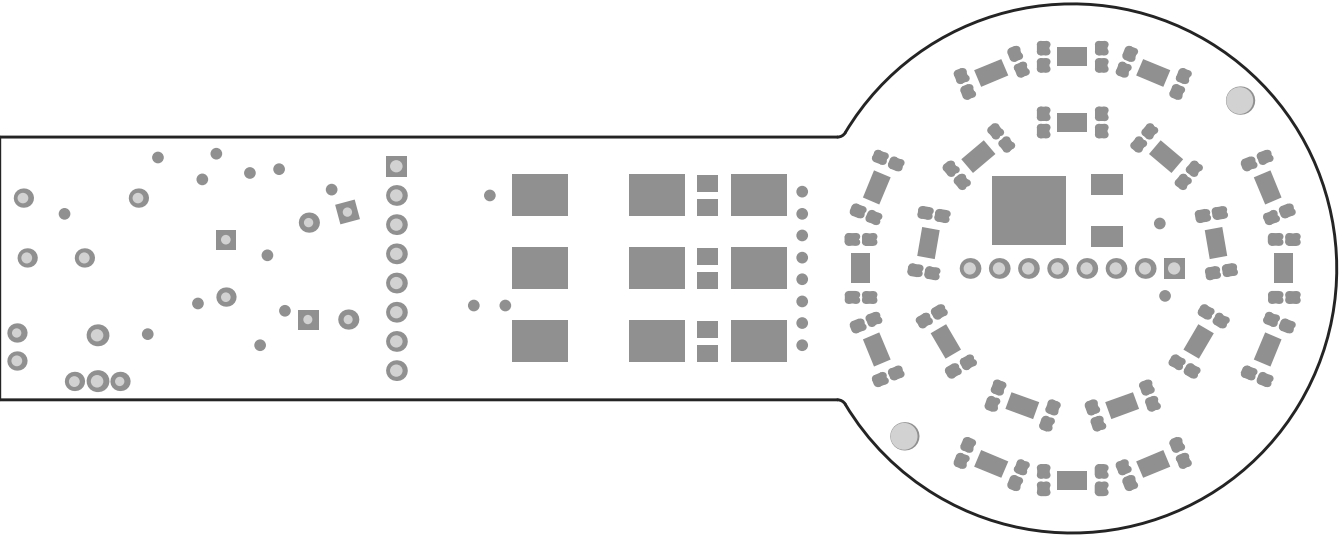
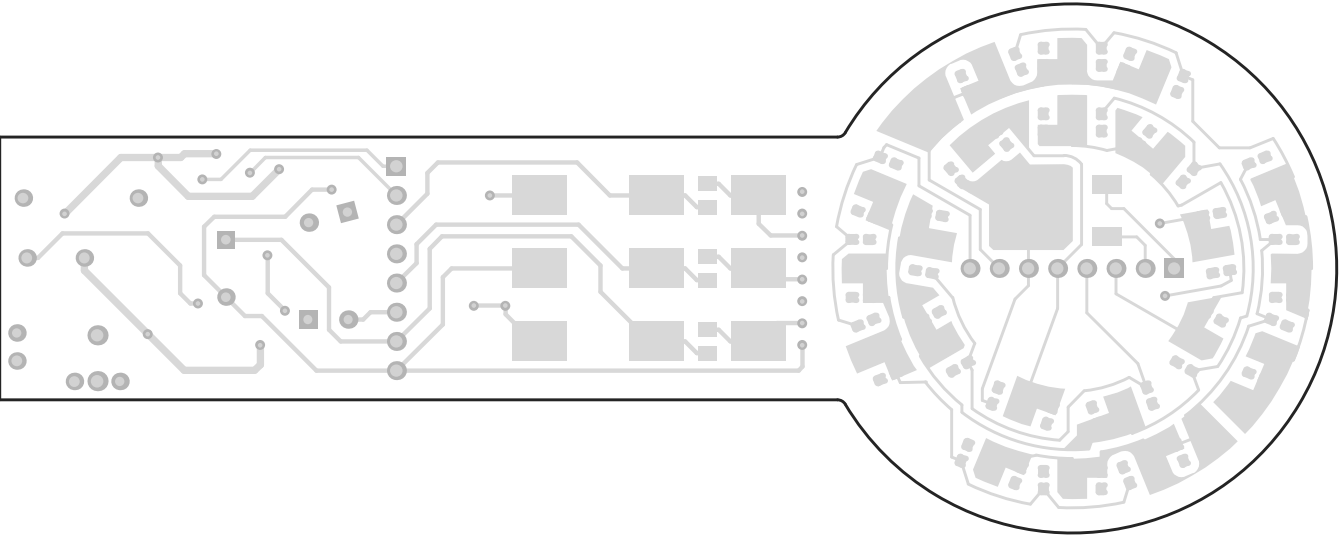




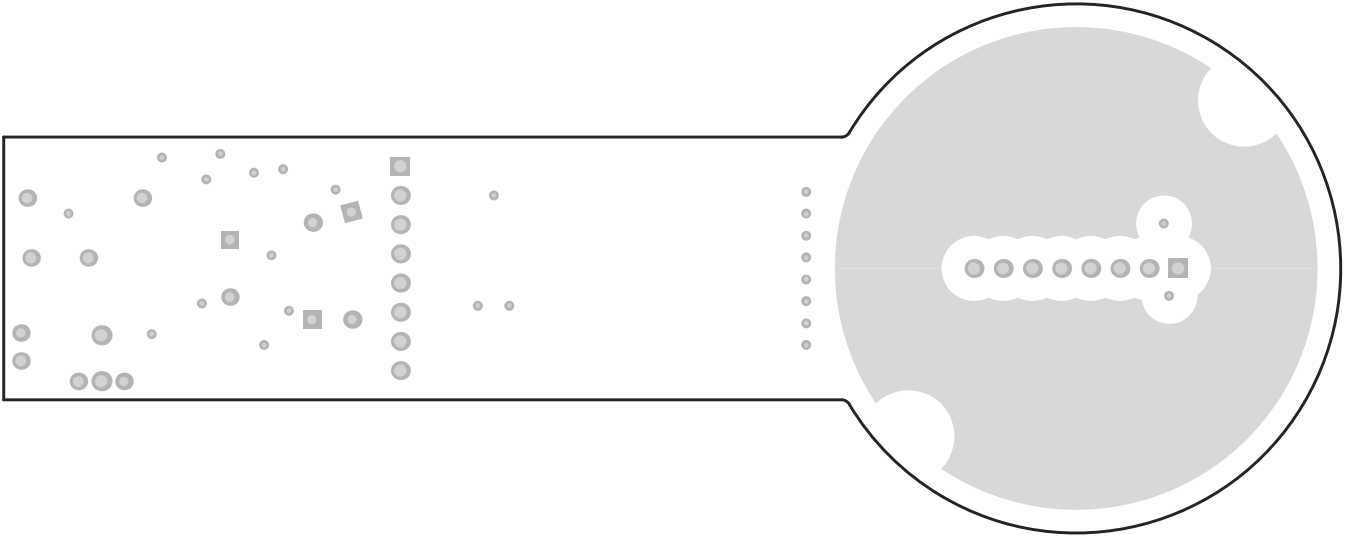
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 7/28/2014 3:42:24 PM		TEXAS INSTRUMENTS



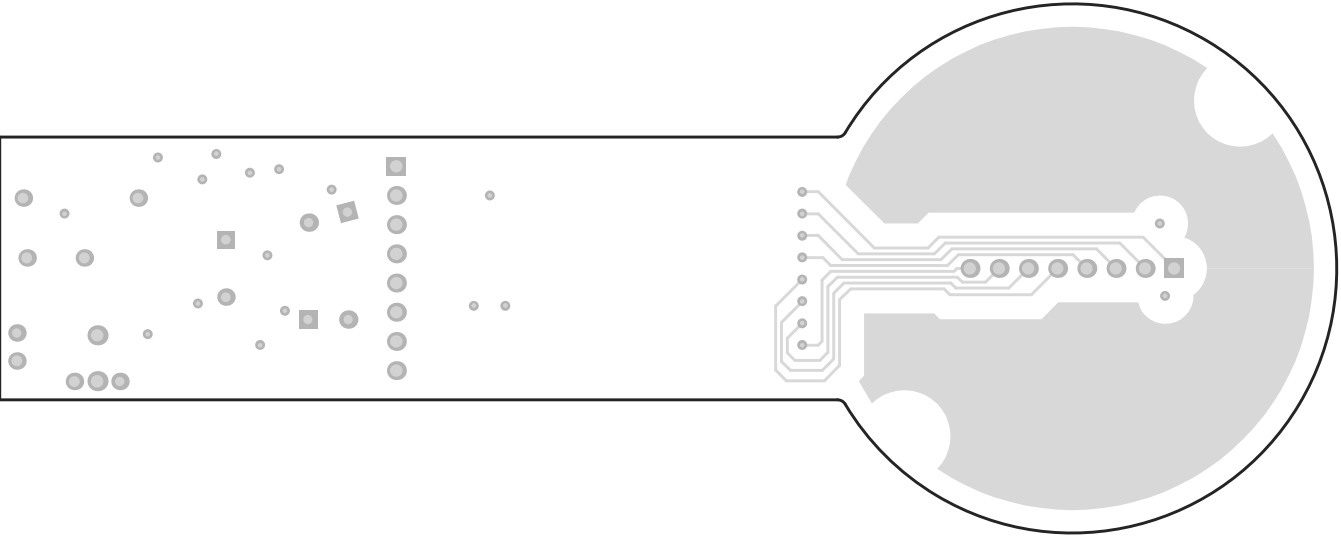
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 7/28/2014 3: 43: 24 PM	TEXAS INSTRUMENTS	



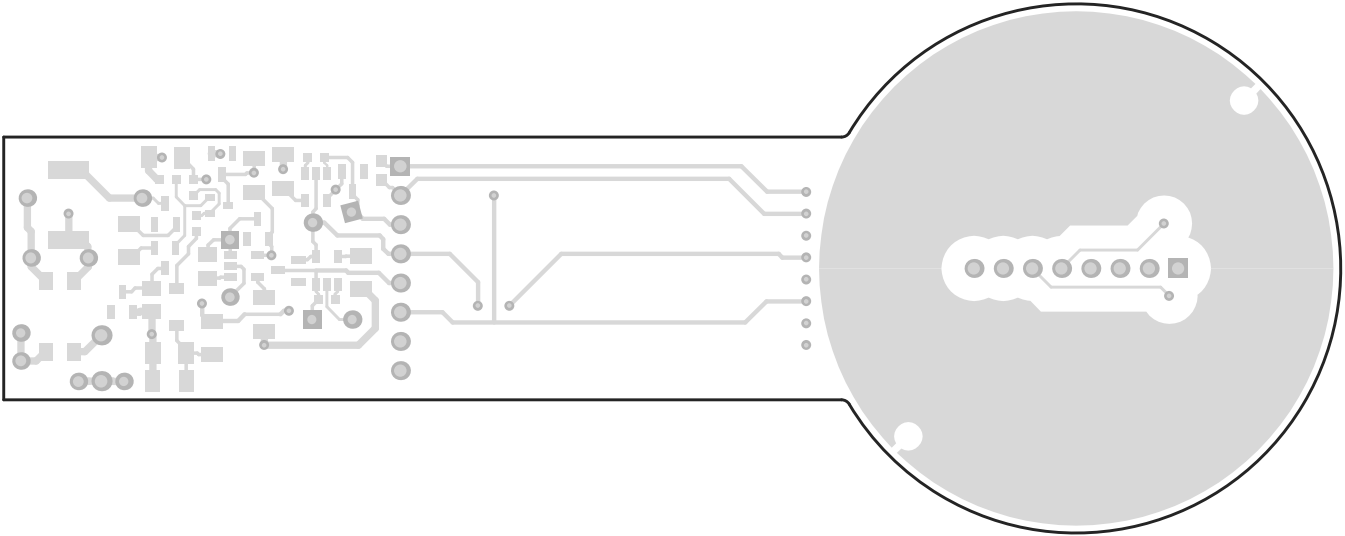
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 7/28/2014 3:44:27 PM	TEXAS INSTRUMENTS	



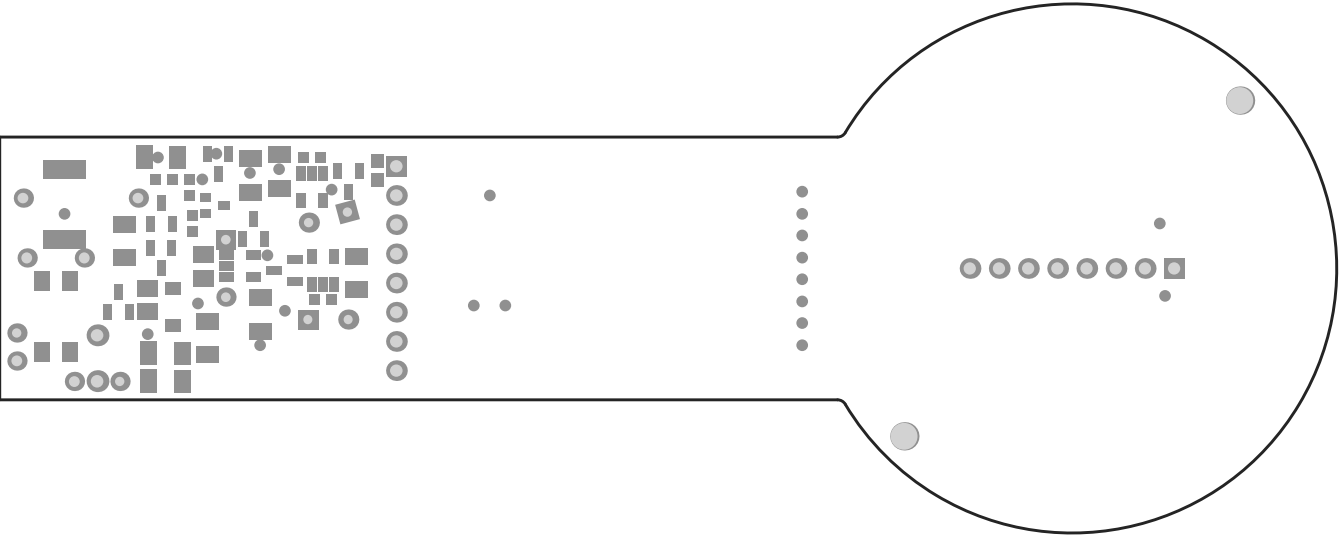
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = MidLayer1			
PLOT NAME = MidLayer1	GENERATED : 7/28/2014 3: 45: 39 PM	TEXAS INSTRUMENTS	



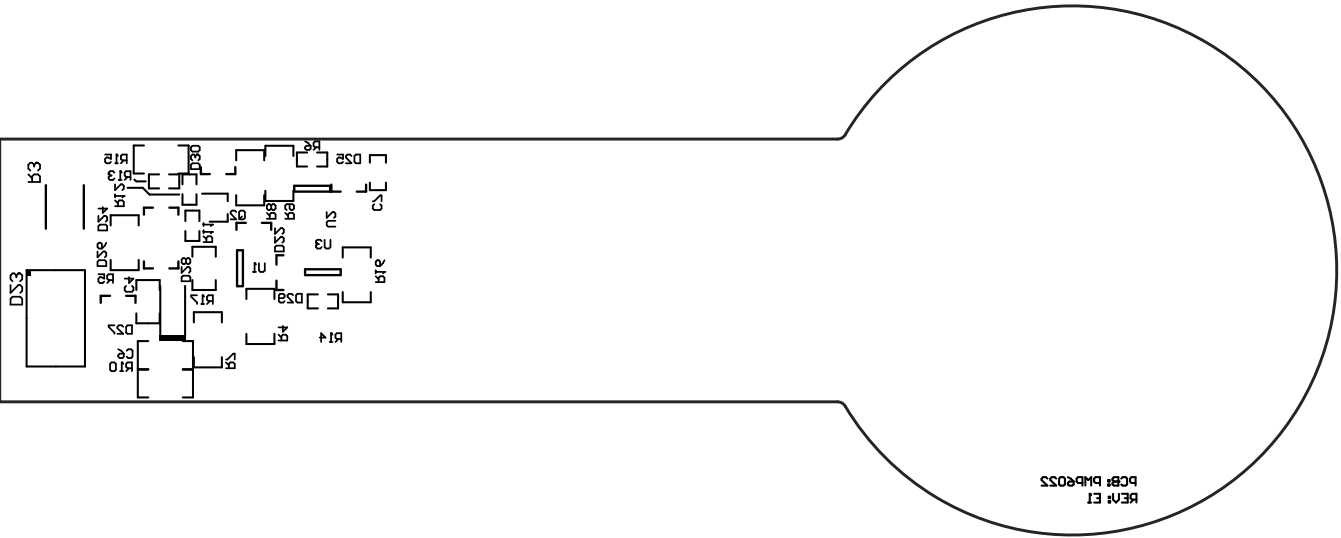
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = MidLayer2			
PLOT NAME = MidLayer2	GENERATED : 7/28/2014 3:46:39 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 7/28/2014 3:47:40 PM	TEXAS INSTRUMENTS	



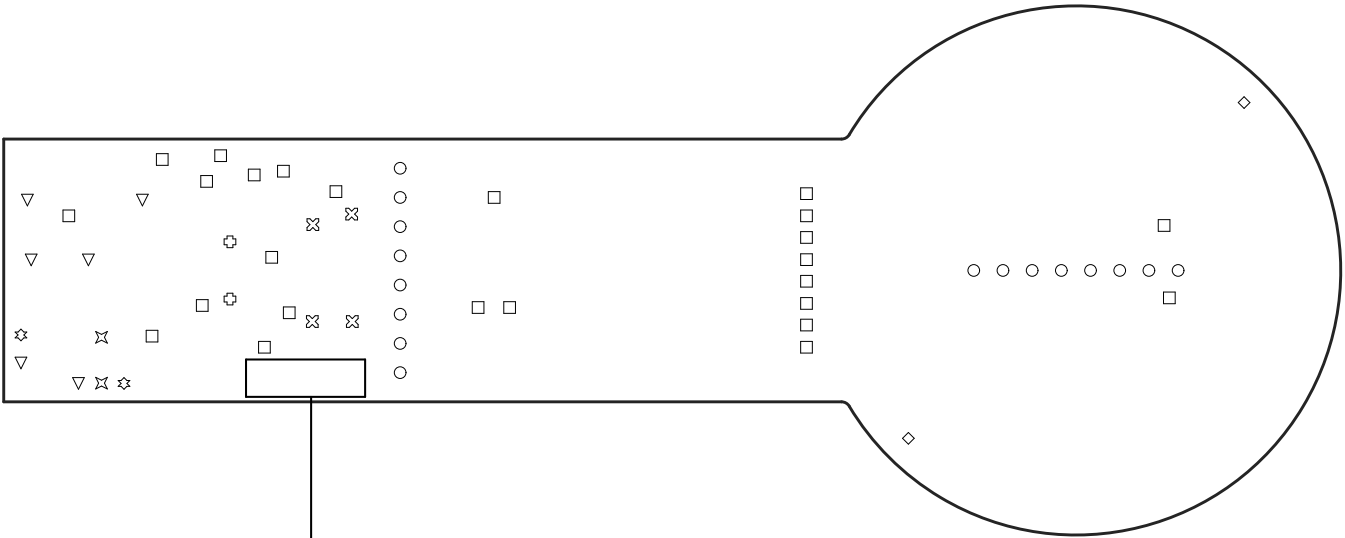
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 7/28/2014 3:48:40 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 7/28/2014 3: 49: 40 PM	TEXAS INSTRUMENTS	

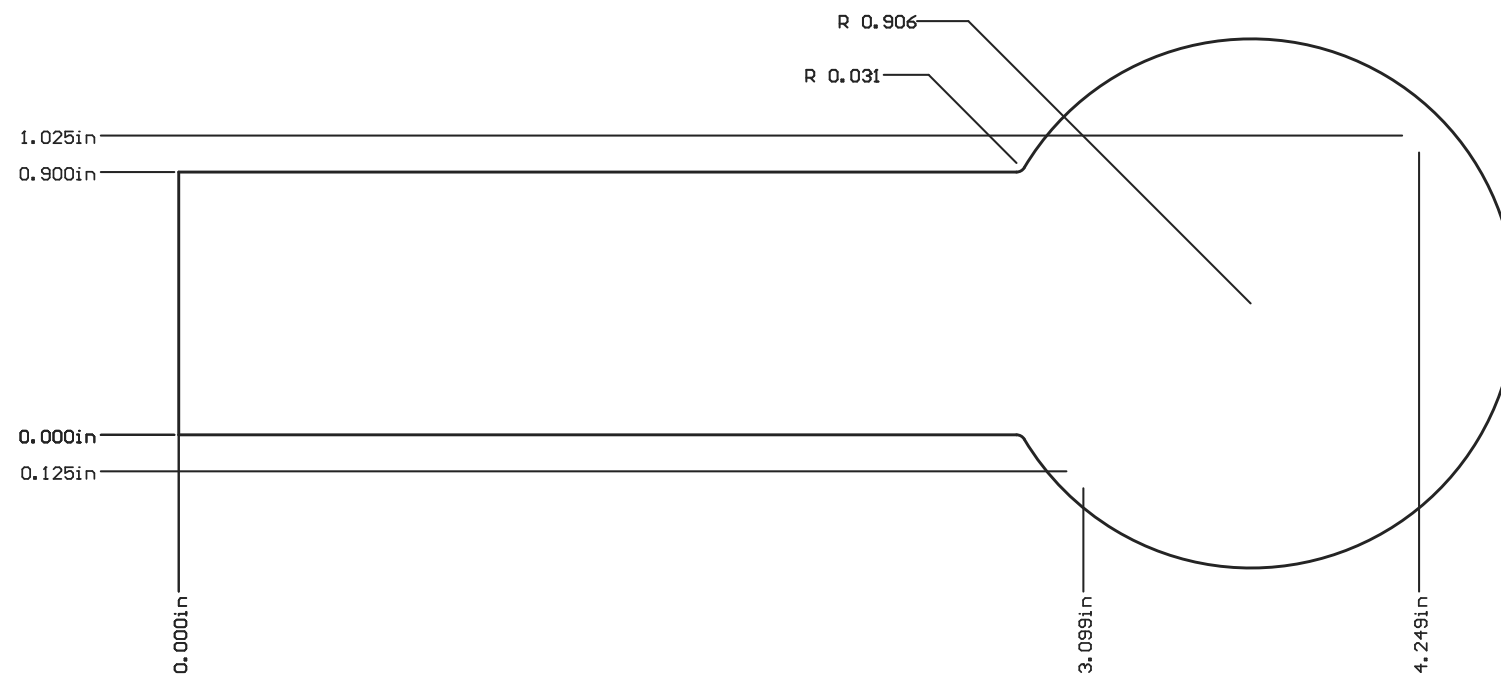
Symbol	Hit Count	Tool Size	Plated	Hole Type
□	25	16mil (0.406mm)	PTH	Round
⊠	4	31.496mil (0.8mm)	PTH	Round
☆	2	32mil (0.813mm)	PTH	Round
⊕	2	33mil (0.838mm)	PTH	Round
▽	6	37mil (0.94mm)	PTH	Round
⊠	2	42.079mil (1.069mm)	PTH	Round
○	16	43mil (1.092mm)	PTH	Round
◇	2	93mil (2.362mm)	NPTH	Round
	59 Total			

Drill Table



PLACE MFGRS LOGO, UL FLAMMABILITY RATING, Tg TEMP, UL FILE NO AND
DATE CODE HERE ON BOTTOM SIDE

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 7/28/2014 3:50:40 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 7/28/2014 3:51:41 PM	TEXAS INSTRUMENTS	

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